





DMC4028SSD

40V COMPLEMENTARY DUAL ENHANCEMENT MODE MOSFET

Product Summary

Device	V _{(BR)DSS}	R _{DS(on)} Max	I _D T _A = +25°C		
Q1	40V	28mΩ @ V _{GS} = 10V 7.			
Qi	400	49mΩ @ V _{GS} = 4.5V	5.4A		
Q2	-40V	50mΩ @ V _{GS} = -10V	-5.2A		
Q2	-4 0 V	79mΩ @ V _{GS} = -4.5V	-4.7A		

Description

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Motor Control
- Backlighting
- DC-DC Converters
- Power Management Functions

Features and Benefits

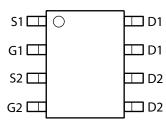
- Low On-Resistance
- · Fast Switching Speed
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

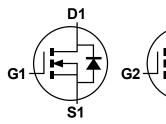
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See diagram below
- Terminals: Finish Matte Tin annealed over Copper lead frame.
 Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.074 grams (approximate)







Top View



Q1 N-Channel

Q2 P-Channel

S₂

D2

Equivalent Circuit

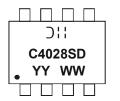
Ordering Information (Note 4)

Part Number Compliance		Case	Packaging
DMC4028SSD-13	Standard	SO-8	2500 / Tape & Reel
DMC4028SSDQ-13	Automotive	SO-8	2500 / Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http"//www.diodes.com/products/packages.html.

Marking Information





);; = Manufacturer's Marking
C4028SD = Product Type Marking Code for DMC4028SSD-13
C4028DQ = Product Type Marking Code for DMC4028SSDQ-13
YYWW = Date Code Marking
YY = Year (ex: 09 = 2009)
WW = Week (01 - 53)





Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	N-Channel - Q1	P-Channel - Q2	Units
Drain-Source Voltage	Drain-Source Voltage			40	-40	V
Gate-Source Voltage (Note 5)		V _{GSS}	±20	±20	V	
	V _{GS} = 10V	(Notes 7 & 9)	lσ	7.2	5.2	Α
Continuous Drain Current		T _A = 70°C (Notes 7 & 9)		5.5	4.2	
		(Notes 6 & 9)		5.4	4	
		(Notes 6 & 10)		6.5	4.8	
Pulsed Drain Current	V _{GS} = 10V	(Notes 7 & 9)	I _{DM}	27.3	20.4	Α
Continuous Source Current (Body diode)		(Notes 7 & 9)	Is	3.35	3.15	Α
Pulsed Source Current (Body diode)		(Notes 8 & 9)	I _{SM}	27.3	20.4	Α

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	N-Channel - Q1	P-Channel - Q2	Unit	
Davis Discipation	(Notes 6 & 9)		1.2 10		
Power Dissipation Linear Derating Factor	(Notes 6 & 10)	P _D	1. 14	W mW/°C	
	(Notes 7 & 9)		2.1 17		
	(Notes 6 & 9)		10	°C/W	
Thermal Resistance, Junction to Ambient	(Notes 6 & 10)	R _{0JA}	7(
	(Notes 7 & 9)		58		
Thermal Resistance, Junction to Lead	(Notes 9 & 11)	$R_{\theta JL}$	53	53	
Operating and Storage Temperature Range		$T_{J_i} T_{STG}$	-55 to	+150	°C

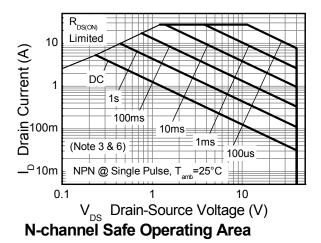
Notes:

- 5. AEC-Q101 V_{GS} maximum is $\pm 16V$.
- 5. ACC-Q101 VQS maximum is ±100.
 6. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
 7. Same as note (5), except the device is measured at t ≤ 10 sec.
 8. Same as note (5), except the device is pulsed with D= 0.02 and pulse width 300 μs. The pulse current is limited by the maximum junction temperature.

- 9. For a dual device with one active die.
- 10. For a device with two active die running at equal power.
- 11. Thermal resistance from junction to solder-point (at the end of the drain lead).

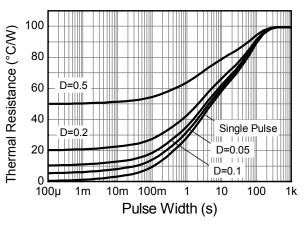


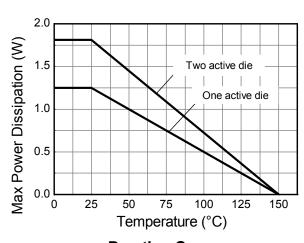
Thermal Characteristics



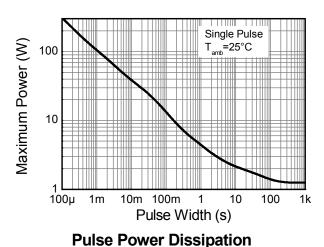
10 R_{DS(ON)} Limited 1 100ms 10ms 10ms 100us PNP @ Single Pulse, T_{amb} =25°C 100 PNP @ Drain-Source Voltage (V)

P-channel Safe Operating Area





Transient Thermal Impedance



Derating Curve





Electrical Characteristics – Q1 N-Channel (@T_A = +25°C, unless otherwise specified.)

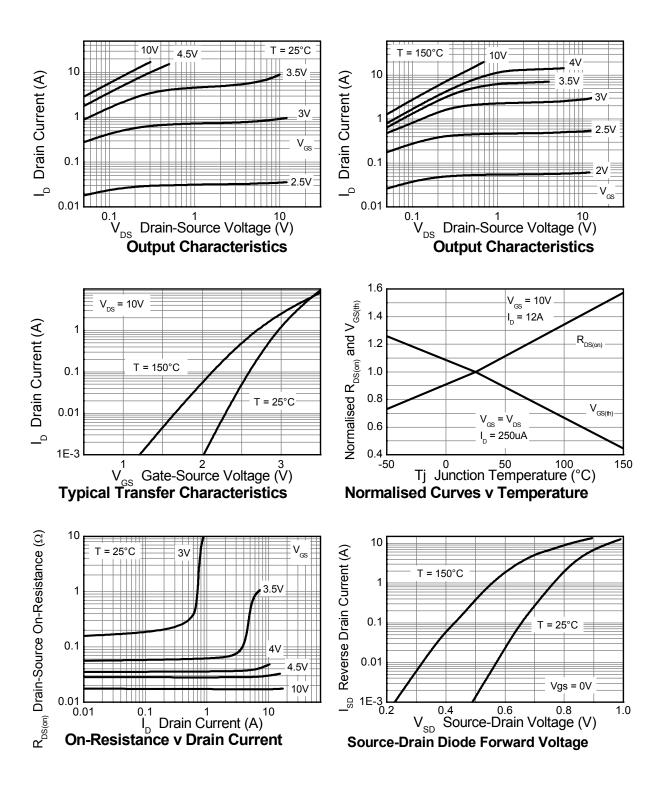
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS								
Drain-Source Breakdown Voltage	BV _{DSS}	40	_	_	V	$I_D = 250 \mu A, V_{GS} =$	I _D = 250μA, V _{GS} = 0V	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	0.5	μA	V _{DS} = 40V, V _{GS} =	• 0V	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	V_{GS} = ±20V, V_{DS}	= 0V	
ON CHARACTERISTICS						_		
Gate Threshold Voltage	V _{GS(th)}	1.0	_	3.0	V	$I_D = 250 \mu A, V_{DS} =$	= V _{GS}	
Static Drain-Source On-Resistance (Note 12)	В		0.018	0.028	Ω	V _{GS} = 10V, I _D = 6	6A	
Static Dialii-Source Oil-Resistance (Note 12)	R _{DS (ON)}	_	0.033	0.049	22	$V_{GS} = 4.5V, I_D = 8$	5A	
Forward Transconductance (Notes 12 & 13)	9 _{fs}	_	22.8	_	S	$V_{DS} = 15V, I_{D} = 6$	A	
Diode Forward Voltage (Note 12)	V _{SD}	_	0.845	1.1	V	I _S = 6A, V _{GS} = 0V	1	
Reverse recovery time (Note 13)	t _{rr}		135	_	ns			
Reverse recovery charge (Note 13)	Q _{rr}	_	799	_	nC	$I_{S} = 6A$, di/dt = 10	JUA/μS	
DYNAMIC CHARACTERISTICS (Note 13)								
Input Capacitance	C _{iss}	_	604	_	pF	.,	0) /	
Output Capacitance	Coss	_	106	_	pF	V _{DS} = 20V, V _{GS} = -f = 1MHz	: 0V	
Reverse Transfer Capacitance	C _{rss}	_	59.6	_	pF	1 - 11/11/12		
Total Gate Charge (Note 14)	Qg	_	6.5	_	nC	V _{GS} = 4.5V		
Total Gate Charge (Note 14)	Q_g	_	12.9	_	nC		V _{DS} = 20V	
Gate-Source Charge (Note 14)	Qgs	_	2.3	_	nC	V _{GS} = 10V	I _D = 6A	
Gate-Drain Charge (Note 14)	Q _{gd}	_	3.6	_	nC	1		
Turn-On Delay Time (Note 14)	t _{D(on)}	_	4.2	_	ns			
Turn-On Rise Time (Note 14)	t _r	_	12.4	_	ns	V_{DD} = 20V, V_{GS} = 10V I_D = 6A, $R_G \approx 6.0\Omega$		
Turn-Off Delay Time (Note 14)	t _{D(off)}	_	13.8	_	ns			
Turn-Off Fall Time (Note 14)	t _f		10.7	_	ns			

Notes:

^{12.} Measured under pulsed conditions. Pulse width $\leq 300 \mu s$; duty cycle $\leq 2\%$ 13. For design aid only, not subject to production testing. 14. Switching characteristics are independent of operating junction temperatures.

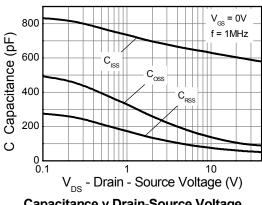


Typical Characteristics - Q1 N-Channel





Typical Characteristics - Q1 N-Channel - (cont.)

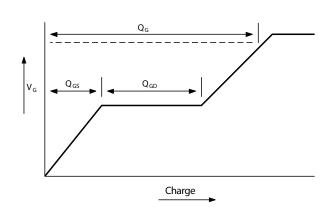


10 Gate-Source Voltage (V) $V_{DS} = 20V$ I_D = 6A \ \ \ SS \ 10 12 6 Q - Charge (nC)

Capacitance v Drain-Source Voltage

Gate-Source Voltage v Gate Charge

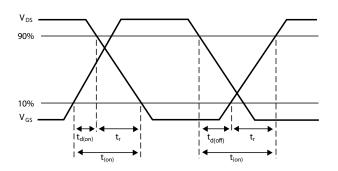
Test Circuits - Q1 N-Channel

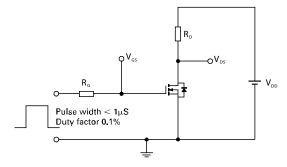


Current regulator J**⊑** ₹ D.U.T

Basic gate charge waveform

Gate charge test circuit





Switching time waveforms

Switching time test circuit





Electrical Characteristics – Q2 P-Channel (@T_A = +25°C, unless otherwise specified.)

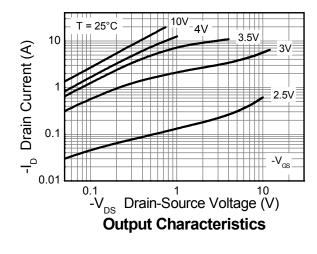
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV _{DSS}	-40	_	_	V	$I_D = -250 \mu A, V_{GS} = 0V$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	-0.5	μA	V _{DS} = -40V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS							
Gate Threshold Voltage	V _{GS(th)}	-1.0	-	-3.0	V	I_D = -250 μ A, V_{DS} = V_{GS}	
Static Drain-Source On-Resistance (Note 12)	Б		0.039	0.050	Ω	V _{GS} = -10V, I _D = -6A	
Static Dialii-Source Off-Resistance (Note 12)	R _{DS(ON)}	_	0.060	0.079	12	V _{GS} = -4.5V, I _D = -5A	
Forward Transconductance (Notes 12 & 13)	g _{fs}	_	16.6	_	S	$V_{DS} = -15V, I_{D} = -6A$	
Diode Forward Voltage (Note 13)	V_{SD}	_	~-0.865	-1.1	V	I _S = -6A, V _{GS} = 0V	
Reverse Recovery Time (Note 13)	t _{rr}	_	138	_	ns	L - CA di/dt - 400A/	
Reverse Recovery Charge (Note 13)	Qrr	_	841	_	nC	$I_S = -6A$, di/dt = 100A/ μ s	
DYNAMIC CHARACTERISTICS (Note 13)							
Input Capacitance	C _{iss}	1	674		pF	.,	
Output Capacitance	Coss		115		pF	V _{DS} = -20V, V _{GS} = 0V f = 1MHz	
Reverse Transfer Capacitance	C _{rss}		67.7		pF	1 - 11/11/2	
Total Gate Charge (Note 14)	Qg	_	7.0	_	nC	V _{GS} = -4.5V	
Total Gate Charge (Note 14)	Qg	_	14	_	nC	V _{DS} = -20V	
Gate-Source Charge (Note 14)	Qgs	_	2.2	_	nC	$V_{GS} = -10V$ $I_D = -6A$	
Gate-Drain Charge (Note 14)	Q_{gd}	_	3.7	_	nC		
Turn-On Delay Time (Note 14)	t _{D(on)}	_	2.3	_	ns		
Turn-On Rise Time (Note 14)	t _r	_	14.1	_	ns	V _{DD} = -20V, V _{GS} = -10V	
Turn-Off Delay Time (Note 14)	t _{D(off)}	_	25.1	_	ns	I_D = -6A, $R_G \cong 6.0\Omega$	
Turn-Off Fall Time (Note 14)	t _f	_	14.3	_	ns		

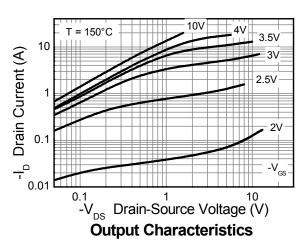
Notes:

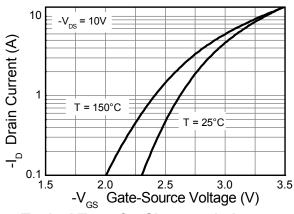
^{12.} Measured under pulsed conditions. Pulse width \leq 300µs; duty cycle \leq 2% 13. For design aid only, not subject to production testing. 14. Switching characteristics are independent of operating junction temperatures.

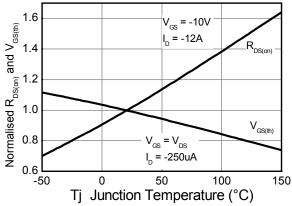


Typical Characteristics - Q2 P-Channel



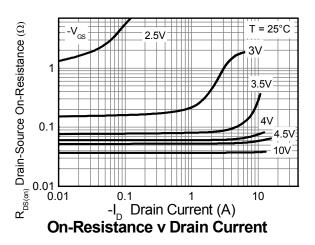


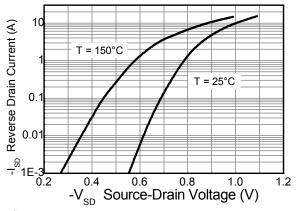




Typical Transfer Characteristics



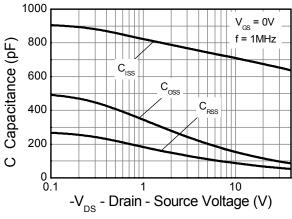




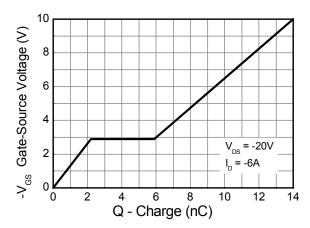
Source-Drain Diode Forward Voltage



Typical Characteristics - Q2 P-Channel - (cont.)

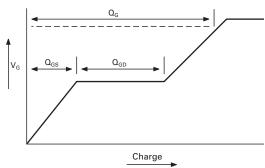


Capacitance v Drain-Source Voltage

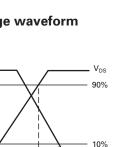


Gate-Source Voltage v Gate Charge

Test Circuits - Q2 P-Channel

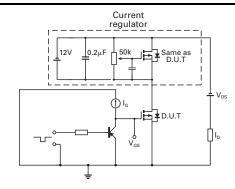


Basic gate charge waveform

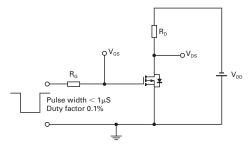


t_{d(on)}

Switching time waveforms



Gate charge test circuit

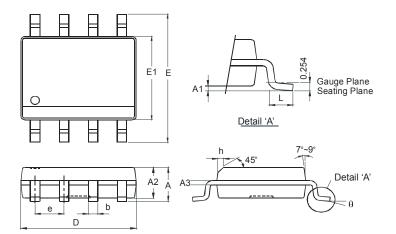


Switching time test circuit



Package Outline Dimensions

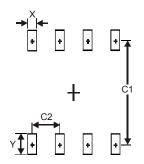
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SO-8					
Dim	Min Max				
Α	-	1.75			
A1	0.10	0.20			
A2	1.30	1.50			
A3	0.15	0.25			
b	0.3	0.5			
D	4.85	4.95			
Е	5.90	6.10			
E1	3.85	3.95			
е	e 1.27 Typ				
h	-	0.35			
L	0.62	0.82			
θ	0° 8°				
All Dimensions in mm					

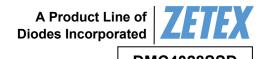
Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27





DMC4028SSD

IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2010, Diodes Incorporated

www.diodes.com

AMEYA360 Components Supply Platform

Authorized Distribution Brand:

























Website:

Welcome to visit www.ameya360.com

Contact Us:

> Address:

401 Building No.5, JiuGe Business Center, Lane 2301, Yishan Rd Minhang District, Shanghai , China

> Sales:

Direct +86 (21) 6401-6692

Email amall@ameya360.com

QQ 800077892

Skype ameyasales1 ameyasales2

Customer Service :

Email service@ameya360.com

Partnership :

Tel +86 (21) 64016692-8333

Email mkt@ameya360.com